

## MOSFET Silicon N-Channel MOS



### 1. Applications

Single-ended flyback or two-transistor forward topologies.  
PC power, PD Adaptor, LCD & PDP TV and LED lighting.

### 2. Features

Low drain-source on-resistance:  $R_{DS(ON)} = 6.5\text{m}\Omega$  (typ.)  
Easy to control Gate switching  
Enhancement mode:  $V_{th} = 2.4$  to  $3.4\text{ V}$

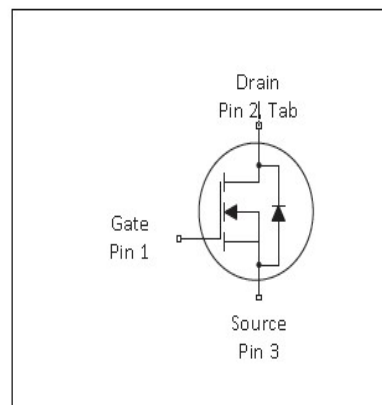


**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	100	V
$R_{DS(on),max}$	7.4	m $\Omega$
$Q_{g,typ}$	60.7	nC
$I_{D,pulse}$	396	A

### 3. Packaging and Internal Circuit

Part Name	Package	Marking
AUP074N10	TO220	AUP074N10



## 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$		-	123	A	$T_C = 25^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	396	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	240	mJ	$T_C = 25^\circ\text{C}$ , $V_{DD} = 50\text{V}$ , $I = 31\text{A}$ , $L = 0.5\text{mH}$ , $R_G = 25\Omega$
Avalanche current, single pulse	$I_{AR}$	-	-	31	A	$T_C = 25^\circ\text{C}$ , $V_{DD} = 50\text{V}$ , $L = 0.5\text{mH}$ , $R_G = 25\Omega$
Gate source voltage (static)	$V_{GS}$	-20	-	20	V	static;
Power dissipation	$P_{tot}$	-	-	175	W	$T_C = 25^\circ\text{C}$
Storage temperature	$T_{stg}$	-55	-	150	$^\circ\text{C}$	
Operating junction temperature	$T_j$	-55	-	150	$^\circ\text{C}$	
Transconductance	GFS	-	51	-	S	$V_{DS} = 5\text{V}$ $I_{DS} = 20\text{A}$

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum Duty Cycle  $D = 0.50$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup> Identical low side and high side switch with identical  $R_G$

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	0.84	°C/W	-
Thermal resistance, junction - ambient	$R_{thJA}$	-	-	60	°C/W	device on PCB, minimal footprint

### 3 Electrical characteristics

at  $T_j=25^{\circ}\text{C}$ , unless otherwise specified

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{(GS)th}$	2.4		3.4	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	$I_{DSS}$	-	-	1	$\mu A$	$V_{DS}=95V, V_{GS}=0V, T_j=25^{\circ}\text{C}$
Gate-source leakage current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	6.5	7.4	m $\Omega$	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Gate resistance (Intrinsic)	$R_G$	-	1.2	-	$\Omega$	$f=1\text{MHz}$ , open drain

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	3680	-	pF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Output capacitance	$C_{oss}$	-	361	-	pF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Reverse transfer capacitance	$C_{rss}$	-	14.6	-	pF	$V_{GS}=0V, V_{DS}=50V, f=1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	-	29	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Rise time	$t_r$	-	55	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Turn-off delay time	$t_{d(off)}$	-	69	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$
Fall time	$t_f$	-	43	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=10\Omega$

**Table 6 Gate charge characteristics**

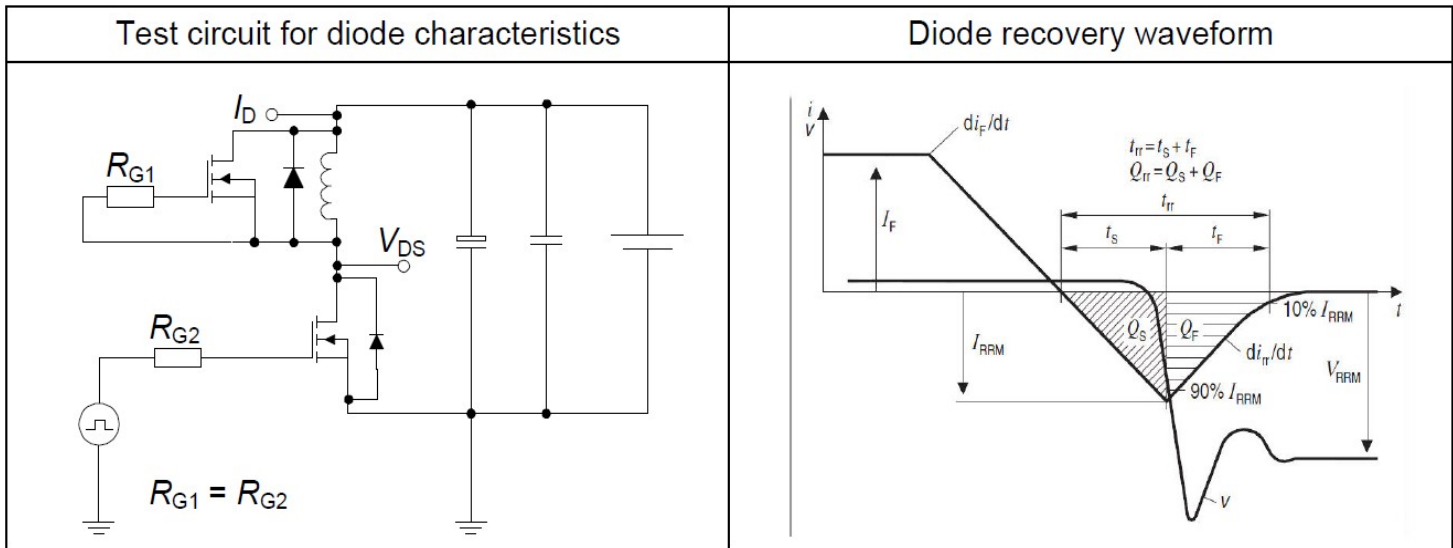
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$	-	15.5	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V
Gate to drain charge	$Q_{gd}$	-	17.6	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V
Gate charge total	$Q_g$	-	60.7	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0$ to 10V

**Table 7 Reverse diode characteristics**

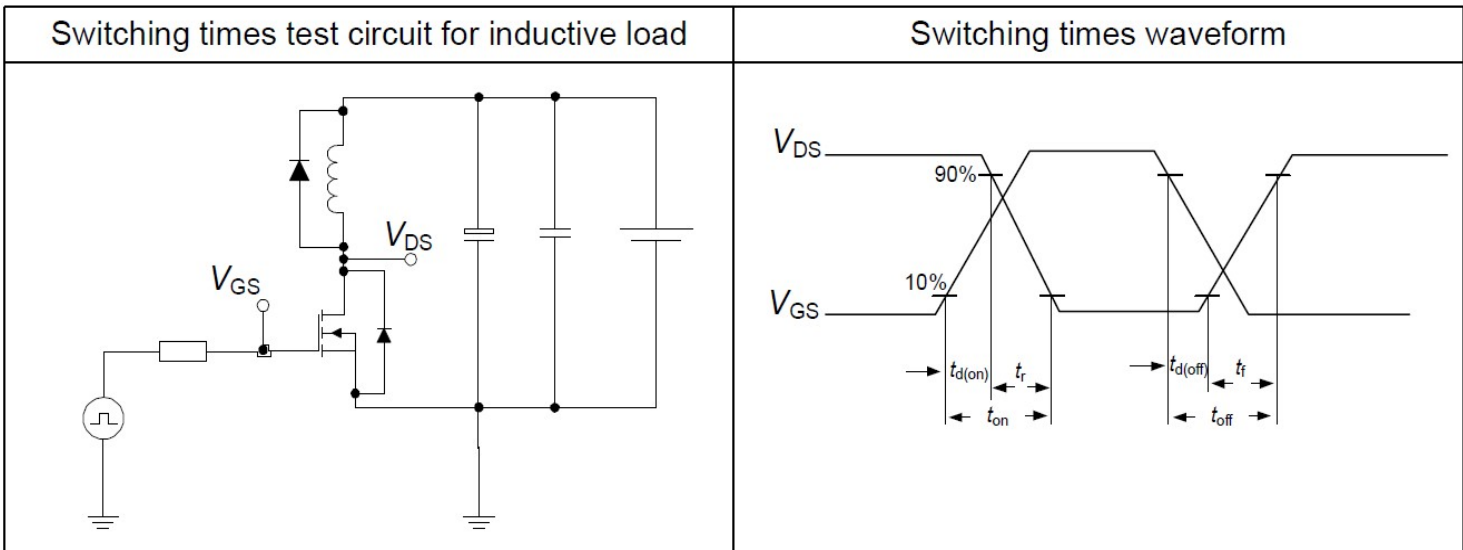
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.7	-	V	$V_{GS}=0V, I_F=1A, T_j=25^\circ C$
Reverse recovery time	$t_{rr}$	-	45	-	ns	$V_R=30V, I_F=20A, di_F/dt=300A/\mu s$
Reverse recovery charge	$Q_{rr}$	-	212	-	nC	$V_R=30V, I_F=20A, di_F/dt=300A/\mu s$
Peak reverse recovery current	$I_{rrm}$	-	8.4	-	A	$V_R=30V, I_F=20A, di_F/dt=300A/\mu s$

## 4 Test Circuits

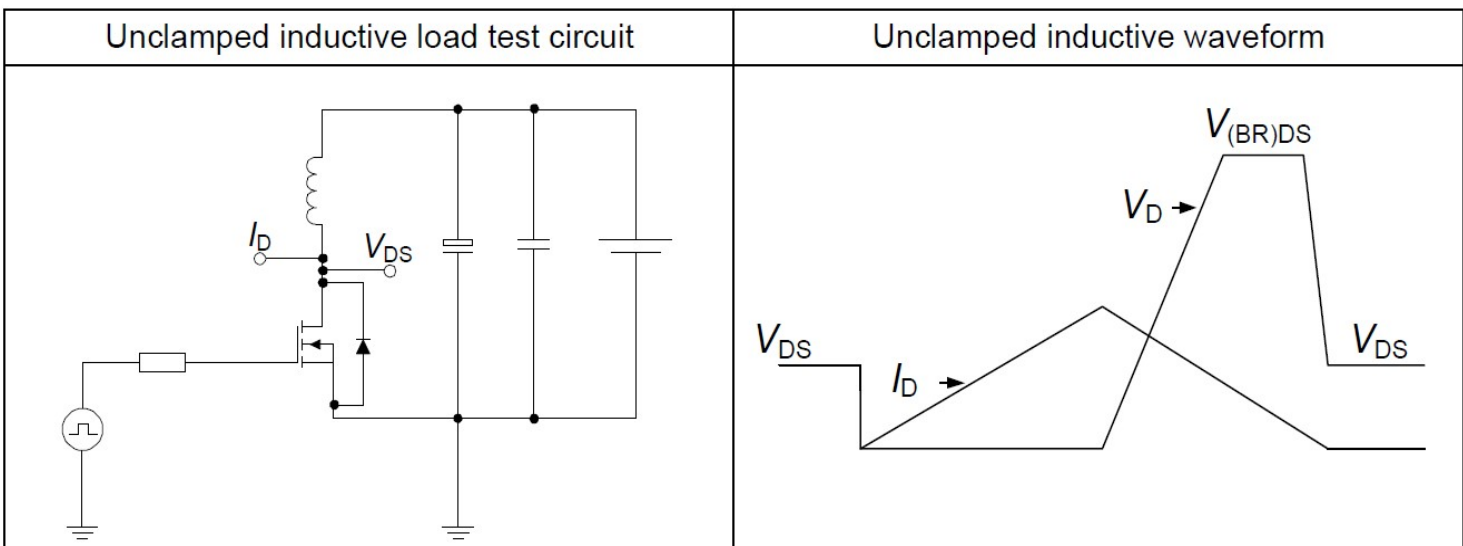
**Table 8 Diode characteristics**



**Table 9 Switching times**



**Table 10 Unclamped inductive load**





## Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2021-10-22	Preliminary version
1.1	2021-11-30	Updated Qrr and EAS